Infrared Light Emitting Diode

1. GENERAL DESCRIPTION

GTR1-IRN01AC-TT/TR is a high power Infrared Emitting Diode in AlGaAs/Si technology & wavelength of 940nm. Molded in clear epoxy (with lens), untinted PCB based SMD package.

2. FEATURES

- Narrow beam angle.
- Good linearity
- High output power
- Capable of pulse operation.
- Floor life: 168 hours, MSL 3, acc. J-STD-020

3. APPLICATIONS

- Emitter for remote control.
- IR touch panels.
- Photo-interrupters
- Optical switch

4. ABSOLUTE MAXIMUM RATINGS at Ta = 25°C

PARAMETER	SYMBOL	MAXIMUM RATING	UNIT
Power Dissipation	P _M	150	mW
Forward Pulse Current*1	I_{FPM}	1.0	A
Forward Current	I_{FM}	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature Range	T_{aop}	-25~+85	$^{\circ}\!\mathbb{C}$
Storage Temperature Range	T_{stg}	-40 ∼+100	$^{\circ}\!\mathbb{C}$
ReflowSolderingTemperature(10Sec.)	$T_{\rm sld}$	250	$^{\circ}\!\mathbb{C}$
HandSolderingTemperature(3Sec.)	T _{sld}	300	$^{\circ}\! \mathbb{C}$
*1:PulseWidth €00 μ s , Duty €%.		Y	

5. ELECTRICAL OPTICAL CHARACTERISTICS at Ta = 25°C

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Radiant Intensity	Ee	10	13	18	mW/sr	$I_F = 20 \text{mA}$
		1	65	1	mW/sr	$I_F = 100 mA$ Pulse Width $\leq 100 \ \mu \text{ s ,Duty} \leq 1\%$
Peak Emission Wavelength	λpeak		940		nm	$I_F = 20 \text{mA}$
Spectral Line Half-Width	Δλ		45		nm	$I_F = 20 \text{mA}$
Forward Voltage	V_{F}		1.33	1.50	V	$I_F = 20 \text{mA}$
Reverse Current	I_R			10	μΑ	$V_R = 5V$
Angle of half intensity	$2\theta_{1/2}$		30		Deg	

6. TYPICAL CHARACTERISTICS

 $(Ta = 25^{\circ}C \text{ Unless Otherwise Noted})$

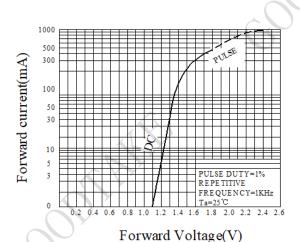


Fig.1 Forward Current Vs Forward Voltage

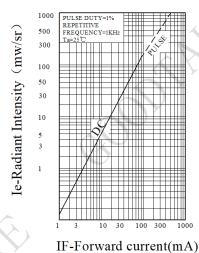


Fig.2 Forward Current Vs Radiant Intensity

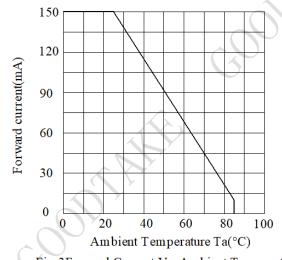


Fig.3Forward Current Vs Ambient Temperature

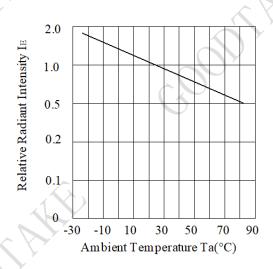


Fig.4 Relative Radiant Intensity Vs Ambient Temperature

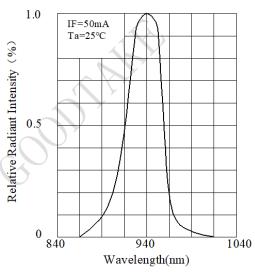
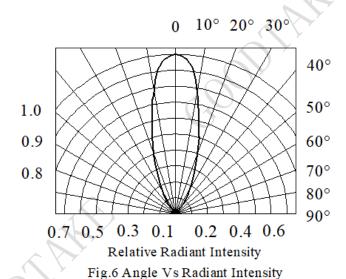
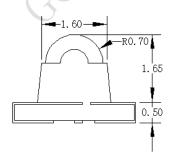
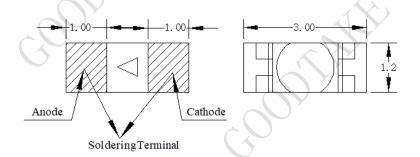


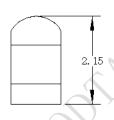
Fig.5 Relative Radiant Intensity Vs Wavelength



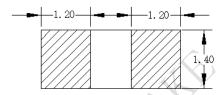
7. PACKAGE DIMENSIONS







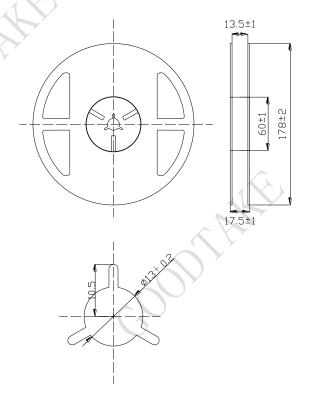
Recommended Solder Pad



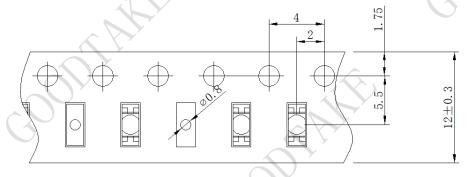
- 1. All dimensions are in millimeters
- 2. Tolerance is ± 0.15 unless otherwise noted

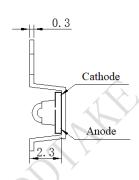
8. PACKAGE DIMENSIONS

(1) Shape and dimensions of reels: unit in mm

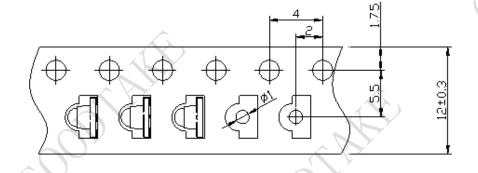


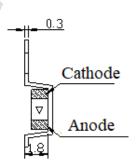
(2) Dimensions of TT tape:



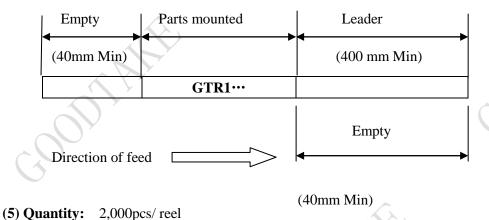


(3) Dimensions of TR tape:





(4) Configuration of tape



9.NOTES:

Antistatic dry packing

Opto devices in SMD package may be sensitive to moisture. Devices are taped & reeled, sealed in antistatic bag with silica gel desiccants.

Do not open the sealed moisture-proof bag before ready to use. If sealing is void, baking treatment may be required.

Storage

Shelf life – Devices should be stored in its original packing, in a controlled environment of temperature less than $40 \, \text{C}$ and relative humidity below 90%.

Suggested shelf life is 12 months in its original packing.

Floor life – MSL3.After opening of the sealed package, the reeled devices should be consumed within 168 hours, in a controlled environment condition of Tamb $< 30 \, \text{C}$, RH = < 60%.

Remaining unused parts should be stored in Dry Box chamber.

Drying (Baking Process)

If original packing is voided (such as faded silica gel or exceeded storage time), baking treatment should be performed with the following conditions:- T storage= $40 + 5 \,\text{C}$, RH <5%, time =192hours.